EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	7	(glass near4 substrate) and interconnect and wafer and chip$2 and active and bump$2 and (flip or turn) and dic$4 and dril$4 and hol$2 and via and plug and scale and package	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 08:40
S2	0	(glass near4 substrate) and interconnect and wafer and chip$2 and active and bump$2 and (flip or turn) and dic$4 and dril$4 and hol$2 and via and plug and scale and package and "indium tin oxide" and eutectic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/14 13:50
S3	4	(glass near4 substrate) and interconnect and wafer and chip$2 and active and bump$2 and (flip or turn) and dic$4 and dril$4 and hol$2 and via and plug and scale and package and "indium tin oxide"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/14 13:50
S4	0	(glass near4 substrate) and interconnect and wafer and chip$2 and active and bump$2 and (flip or turn) and dic$4 and dril$4 and hol$2 and via and plug and scale and package and "indium tin oxide" and ACF	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/14 13:50
S5	4	(glass near4 substrate) and interconnect and wafer and chip$2 and active and bump$2 and (flip or turn) and dic$4 and dril$4 and hol$2 and via and plug and scale and package and "indium tin oxide"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 10:48
S6	0	"glass substrate" near8 interconnect and (bump or ball) and chips and wafer and dic$4 and hole and (via near8 plug) and (scale near8 package)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 10:52
S7	0	"glass substrate" near8 interconnect and (bump or ball) and chips and wafer and dic$4 and hole and (via near8 plug)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 10:52

S8	58	substrate near8 interconnect and (bump or ball) and chips and wafer and dic$4 and hole and (via near8 plug)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 10:52
S9	58	(substrate near8 interconnect) and (bump or ball) and chips and wafer and dic$4 and hole and (via near8 plug)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 10:52
S10	47	(substrate near8 interconnect) and (bump or ball) and chips and wafer and dic$4 and hole and (via near8 plug) and glass	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 10:52
S11	0	(substrate near8 interconnect) and (bump or ball) and chips and wafer and dic$4 and hole and (via near8 plug) and glass and drill	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 10:53
S12	0	(substrate near8 interconnect) and (bump or ball) and chips and wafer and dic$4 and hole and (via near8 plug) and glass and scribe	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 10:53
S13	47	(substrate near8 interconnect) and (bump or ball) and chips and wafer and dic$4 and hole and (via near8 plug) and glass	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 11:06
S14	0	(substrate near8 interconnect) and (bump or ball) and chips and wafer and dic$4 and hole and (via near8 plug) and glass and "indium tin oxide"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 10:55
S15	6	(substrate near8 interconnect) and (bump or ball) and chips and wafer and dic$4 and hole and (via near8 plug) and glass and eutectic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 10:57

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S16	0	(substrate near8 interconnect) and (bump or ball) and chips and wafer and dic$4 and hole and (via near8 plug) and glass and eutectic and ACF	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 10:56
S17	0	(substrate near8 interconnect) and (bump or ball) and chips and wafer and dic$4 and hole and (via near8 plug) and glass and eutectic and anisotropic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 10:57
S18	0	(drill near8 substrate) and interconnect and wafer and chips and bumps and dic$4 and holes and (via near4 plug)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 11:08
S19	10915	drill and substrate	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 11:50
S20	16	drill and substrate and interconnect and wafer and chips and bumps and dic$4 and via and plugs	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 11:52
S21	11	drill and substrate and interconnect and wafer and chips and bumps and dic$4 and via and plugs and (scale near4 package)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 12:00
S22	11	drill and substrate and interconnect and wafer and chips and bumps and dic$4 and via and plugs and (scale near4 package) and glass	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 11:53
S23	0	drill and substrate and interconnect and wafer and chips and bumps and dic$4 and via and plugs and (scale near4 package) and glass and "indium tin oxide"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 11:53

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S24	0	drill and substrate and interconnect and wafer and chips and bumps and dic$4 and via and plugs and (scale near4 package) and glass and scribe	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 11:54
S25	0	drill and substrate and interconnect and wafer and cover and chips and scribe and pads and dic$4 and (via near4 plugs) and (scale near4 package) and glass	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 11:56
S26	6	drill and substrate and interconnect and wafer and chips and bumps and dic$4 and via and plugs and (scale near4 package) and scrib$4 and pads	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 12:55
S27	3	drill and substrate and interconnect and wafer and chips and bumps and dic$4 and via and plugs and (scale near4 package) and scrib$4 and pads .clm.	US-PGPUB	OR	ON	2005/09/15 13:18
S28	0	drill and substrate and interconnect and wafer and chips and bumps and dic$4 and via and plugs and (scale near4 package) and scrib$4 and pads and (438/106.ccls.)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:20
S29	1	drill and substrate and interconnect and wafer and chips and bumps and dic$4 and via and plugs and (scale near4 package) and scrib$4 and pads and (438/108.ccls.)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/15 13:20
S30	3	drill and substrate and interconnect and wafer and chips and bumps and dic$4 and via and plugs and (scale near4 package) and scrib$4 and pads and (438/113.ccls.)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 12:57
S31	9	"6908784"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/30 12:58

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S32	0	"CSP" and eutectic and "ACF" and plat$3 and plug$2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 08:42
S33	0	eutectic and "ACF" and plat$3 and plug$2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 08:42
S34	1482	eutectic and anisotropic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 08:42
S35	190	eutectic and "anisotropic conductive film"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 08:42
S36	11	eutectic and "anisotropic conductive film" and "indium tin oxide"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 08:43
S37	11	eutectic and "anisotropic conductive film" and "indium tin oxide" and plat$3	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 10:57
S38	0	eutectic and "anisotropic conductive film" and "indium tin oxide" and plat$3 and plug	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/12/01 10:57
S39	12747	"CSP"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/18 12:39

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S40	1235	"CSP" and (glass near4 (substrate or semiconductor or wafer))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/04 07:27
S41	135	"CSP" and (glass near4 (substrate or semiconductor or wafer)) and interconnect near4 (substrate or semiconductor or wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/18 12:41
S42	1125	"CSP" and (glass near4 substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/18 12:41
S43	7	"CSP" and ((glass near4 substrate) near4 interconnect)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/18 12:42
S44	5	"CSP" and ((glass near4 substrate) near4 interconnect) and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/18 12:42
S45	3	"CSP" and ((glass near4 substrate) near4 interconnect) and wafer and chip$2 and bump$2 and flip	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/18 12:43
S46	1	"CSP" and ((glass near4 substrate) near4 interconnect) and wafer and chip$2 and bump$2 and flip and (dic$4 near4 wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/18 12:43
S47	1	"CSP" and ((glass near4 substrate) near4 interconnect) and wafer and chip$2 and bump$2 and flip and (dic$4 near4 wafer) and via	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/18 12:45

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S48	4	"CSP" and ((glass near4 substrate) near4 (interconnect or metal)) and wafer and chip$2 and bump$2 and flip and (dic$4 near4 wafer) and via	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/18 12:46
S49	1	"CSP" and ((glass near4 substrate) near4 (interconnect or metal)) and wafer and chip$2 and bump$2 and flip and (dic$4 near4 wafer) and via and (dic$4 near4 glass)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/18 12:47
S50	23	"CSP" and ((glass near4 (substrate or plate)) near4 (interconnect or metal)) and eutectic	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/18 12:48
S51	11	"CSP" and ((glass near4 (substrate or plate)) near4 (interconnect or metal)) and eutectic and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/18 12:49
S52	7	"CSP" and ((glass near4 (substrate or plate)) near4 (interconnect or metal)) and eutectic and (dic$4 near4 wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/18 12:50
S53	4	"CSP" and ((glass near4 (substrate or plate)) near4 (interconnect or metal)) and eutectic and (dic$4 near4 wafer) and (dic$4 near4 substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/18 12:56
S54	2	"CSP" and ((glass near4 (substrate or plate)) near4 (interconnect or metal)) and eutectic and (dic$4 near4 wafer) and (dic$4 near4 substrate) and flip	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/18 12:51
S55	682	"CSP" and die$2 and (pad or interconnect) and adhesive and substrate and (solder near4 ball) and via	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/18 12:57

S56	36	"CSP" and die$2 and (pad or interconnect) and adhesive and substrate and (solder near4 ball) and via and (scribe near4 line)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/18 12:59
S57	7	"CSP" and die$2 and (pad or interconnect) and adhesive and substrate and (solder near4 ball) and via and (scribe near4 line) and drill$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/18 13:16
S58	1	"CSP" and die$2 and (pad or interconnect) and adhesive and substrate and (solder near4 ball) and via and (scribe near4 line) and drill$4 and (257/734.ccls.)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/18 14:47
S59	0	"CSP" and die$2 and (pad or interconnect) and adhesive and substrate and (solder near4 ball) and via and (scribe near4 line) and drill$4 and (438/106,108,113.ccls.)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/07/18 14:47
S60	1473	("CSP" or "chip scale package") and (glass near4 (substrate or semiconductor or wafer))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/04 07:28
S61	509	("CSP" or "chip scale package") and (glass near4 (substrate or semiconductor or wafer)) and (plurality near4 chip)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/04 07:29
S62	451	("CSP" or "chip scale package") and (glass near4 (substrate or semiconductor or wafer)) and ((plurality near4 chip) near8 (wafer or substrate or semiconductor))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/04 07:30
S63	159	("CSP" or "chip scale package") and (glass near4 (substrate or semiconductor or wafer)) and ((plurality near4 chip) near8 (wafer or substrate or semiconductor)) and (plurality near4 bump$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/04 07:31

S64	45	("CSP" or "chip scale package") and (glass near4 (substrate or semiconductor or wafer)) and ((plurality near4 chip) near8 (wafer or substrate or semiconductor)) and (plurality near4 bump$3) and (flip$4 near8 (wafer or substrate or semiconductor))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/04 07:31
S65	12	("CSP" or "chip scale package") and (glass near4 (substrate or semiconductor or wafer)) and ((plurality near4 chip) near8 (wafer or substrate or semiconductor)) and (plurality near4 bump$3) and (flip$4 near8 (wafer or substrate or semiconductor)) and interconnect	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/04 07:32
S66	45	("CSP" or "chip scale package") and (glass near4 (substrate or semiconductor or wafer)) and ((plurality near4 chip) near8 (wafer or substrate or semiconductor)) and (plurality near4 bump$3) and (flip$4 near8 (wafer or substrate or semiconductor)) and connect$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/04 07:32
S67	33	("CSP" or "chip scale package") and (glass near4 (substrate or semiconductor or wafer)) and ((plurality near4 chip) near8 (wafer or substrate or semiconductor)) and (plurality near4 bump$3) and (flip$4 near8 (wafer or substrate or semiconductor)) and connect$4 and (dic$4 or cut)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/04 07:33
S68	29	("CSP" or "chip scale package") and (glass near4 (substrate or semiconductor or wafer)) and ((plurality near4 chip) near8 (wafer or substrate or semiconductor)) and (plurality near4 bump$3) and (flip$4 near8 (wafer or substrate or semiconductor)) and connect$4 and ((dic$4 or cut) near8 (substrate or semiconductor or wafer))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/04 07:34

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S69	1	("CSP" or "chip scale package") and (glass near4 (substrate or semiconductor or wafer)) and ((plurality near4 chip) near8 (wafer or substrate or semiconductor)) and (plurality near4 bump$3) and (flip$4 near8 (wafer or substrate or semiconductor)) and connect$4 and ((dic$4 or cut) near8 (substrate or semiconductor or wafer)) and (drill$4 near8 wafer)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/04 07:35
S70	4	("CSP" or "chip scale package") and (glass near4 (substrate or semiconductor or wafer)) and ((plurality near4 chip) near8 (wafer or substrate or semiconductor)) and (plurality near4 bump$3) and (flip$4 near8 (wafer or substrate or semiconductor)) and connect$4 and ((dic$4 or cut) near8 (substrate or semiconductor or wafer)) and (drill$4 near8 (wafer or semiconductor or substrate))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/04 07:35
S71	4	("CSP" or "chip scale package") and (glass near4 (substrate or semiconductor or wafer)) and ((plurality near4 chip) near8 (wafer or substrate or semiconductor)) and (plurality near4 bump$3) and (flip$4 near8 (wafer or substrate or semiconductor)) and connect$4 and ((dic$4 or cut) near8 (substrate or semiconductor or wafer)) and (drill$4 near8 (wafer or semiconductor or substrate)) and plug	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/04 07:36

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S72	4	("CSP" or "chip scale package") and (glass near4 (substrate or semiconductor or wafer)) and ((plurality near4 chip) near8 (wafer or substrate or semiconductor)) and (plurality near4 bump$3) and (flip$4 near8 (wafer or substrate or semiconductor)) and connect$4 and ((dic$4 or cut) near8 (substrate or semiconductor or wafer)) and (drill$4 near8 (wafer or semiconductor or substrate)) and plug and (via near4 hole)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/04 07:54
S73	2	("CSP" or "chip scale package") and (glass near4 (substrate or semiconductor or wafer)) and ((plurality near4 chip) near8 (wafer or substrate or semiconductor)) and (plurality near4 bump$3) and (flip$4 near8 (wafer or substrate or semiconductor)) and connect$4 and ((dic$4 or cut) near8 (substrate or semiconductor or wafer)) and "CTE"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/04 07:56
S74	2	("CSP" or "chip scale package") and (glass near4 (substrate or semiconductor or wafer)) and ((plurality near4 chip) near8 (wafer or substrate or semiconductor)) and (plurality near4 bump$3) and (flip$4 near8 (wafer or substrate or semiconductor)) and connect$4 and ((dic$4 or cut) near8 (substrate or semiconductor or wafer)) and ("CTE" or "coefficient of thermal expansion")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/04 07:58
S75	137	("CSP" or "chip scale package") and (glass near4 (substrate or semiconductor or wafer)) and ("CTE" or "coefficient of thermal expansion")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/04 07:58
S76	437178	("CSP" or "chip scale package") and (glass near4 (substrate or semiconductor or wafer)) and ("CTE" or "coefficient of thermal expansion") and "indium tin oxide" or "ITO"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/04 07:59

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S77	5	("CSP" or "chip scale package") and (glass near4 (substrate or semiconductor or wafer)) and ("CTE" or "coefficient of thermal expansion") and ("indium tin oxide" or "ITO")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/08/04 07:59
S78	291	(wafer near4 (scale or level)) and (packag$4 or encapsulat$4 or encapsulant or epoxy or underfill) and (second near4 (cut or saw))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/01 13:29
S79	47	(wafer near4 (scale or level)) and (packag$4 or encapsulat$4 or encapsulant or epoxy or underfill) and (second near4 (cut or saw)) and (glass near4 substrate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/29 10:16
S80	11	(wafer near4 (scale or level)) and (packag$4 or encapsulat$4 or encapsulant or epoxy or underfill) and (second near4 (cut or saw)) and (glass near4 substrate) and interconnect and flip$4 and wafer	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/01 13:44
S81	14	"6022758"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/01 13:44
S82	1	(wafer near4 (scale or level)) and (packag$4 or encapsulat$4 or encapsulant or epoxy or underfill) and (second near4 (cut or saw)) and (glass near4 substrate) and (257/734.ccls.)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/09/29 10:17